

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10810965			
<b>Filing Date:</b>	26-Mar-2004			
<b>Title of Invention:</b>	Novel method to improve bump reliability for flip chip device			
First Named Inventor/Applicant Name:	Yen-Ming Chen			
<b>Filer:</b>	Daniel R. McClure			
<b>Attorney Docket Number:</b>	TS01-0413C			
Filed as Large Entity				
<b>Utility      Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Filing a brief in support of an appeal	1402	1	500	500
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				500